

| Construction element | Material group | Materials | CAS (where available) | Average mass (%) | Sum (%) | Mass (mg) | ppm |
|------------------------|-----------------------|---|-----------------------|------------------|---------|-----------|--------|
| Chip | Silicon | Silicon | 7440-21-3 | 1.15 | 1.15 | 1.83 | 11501 |
| Leadframe | Copper Alloy | Copper | 7440-50-8 | 54.03 | 55.49 | 85.90 | 540252 |
| | | Iron | 7439-89-6 | 1.33 | | 2.12 | 13318 |
| | | Zinc | 7440-66-6 | 0.07 | | 0.12 | 723 |
| | | Phosphorus | 7723-14-0 | 0.04 | | 0.07 | 447 |
| | | Lead | 7439-92-1 | 0.02 | | 0.03 | 167 |
| Leadframe plating | Silver | Silver | 7440-22-4 | 0.20 | 0.20 | 0.31 | 1979 |
| Wires | Gold wire | Gold wire | 7440-57-5 | 0.11 | 0.11 | 0.17 | 1073 |
| Encapsulation | Filled silicone resin | Cristobalite | 14464-46-1 | 0.11 | 40.41 | 0.18 | 1126 |
| | | Amorphous Fused Silicon | 60676-86-0 | 26.49 | | 42.12 | 264906 |
| | | Fibrous Glass | 65997-17-3 | 6.30 | | 10.01 | 62956 |
| | | Carbon Black | 1333-86-4 | 0.11 | | 0.18 | 1126 |
| | | Amorphous Silica | 7631-86-9 | 0.88 | | 1.40 | 8805 |
| | | Quartz | 14808-60-7 | 0.11 | | 0.18 | 1126 |
| | | Octamethylcyclotetrasiloxane | 556-67-2 | 0.11 | | 0.18 | 1126 |
| | | Phenylsilsesquioxane-dimethylsiloxane copolymer | 73138-88-2 | 6.30 | | 10.01 | 62956 |
| Alternative Leadfinish | Tin only | Tin | 7440-31-5 | 2.42 | | 4.20 | 26411 |
| Sum in Total: | | | | | 100.00 | 159.00 | |

| | |
|--------------------|------|
| Fluctuation margin | ±10% |
|--------------------|------|

This environmental data is based on information provided by our suppliers; we believe it to be correct but do not routinely validate it by measurement.

The information is for guidance only, and Zetex does not guarantee its absolute accuracy or completeness.

The active part of each device is a silicon chip doped at atomic levels (some tens of ppb) with Phosphorus, Boron and Arsenic. The back of the die is raw or metallized with thin layers of Titanium, Nickel, Silver or Gold in order to enhance the die bonding to the header or leadframe. These and other substances are not reported as being present in Zetex products where their concentration is less than 20ppm, as they are not considered detectable by normal analytical methods.

The lead contained within the leadframe alloy is exempted from the RoHS Directive 2002/95/EC as defined in clauses 6 & 7 of the Annex.

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